



Suitable for BIOMETRIC sensor lamination

Features & description

The BGi100 is an automatic glue tape lamination equipment (dimension of reel: 35mm width).

- Stand alone equipment with automatic hotmelt and chip feeding
- Screen touch interface (30 programs memorized)

Advantages

- Compact and easy with a throughput of 10 000 units per hour
- Easy adjustment of time, pressure and temperature parameters

Option BGI110a

- BGI100a is the punch tool allowing to punch the hotmelt tape before lamination (glob top at the back of the chips or biometric sensor)

Description

- Width: 1480mm
- Depth: 480mm
- Height: 1650mm
- Weight: 85kg

Facilities

- Power: 100-240V AC
- Frequency: 50-60Hz single phase
- Power consumption: 350W maximum
- Pneumatic characteristics: 6 bars

Throughput

- Up to 10 000 units/hour

Environmental conditions

- Operating temperature: +10°C to +40°C